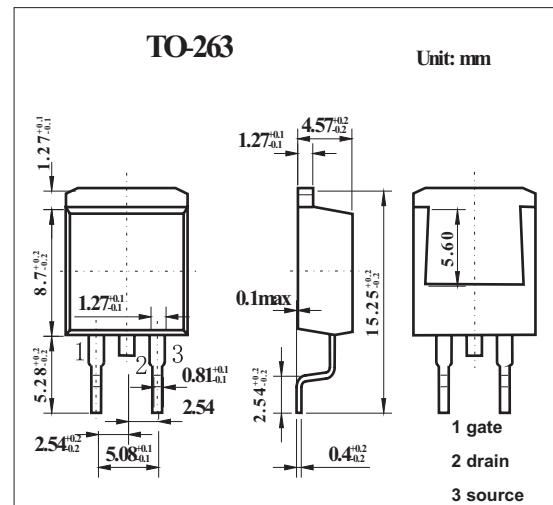
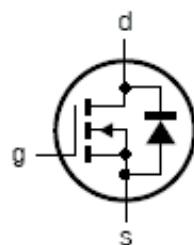


TrenchMOS™ standard level FET

KUK7607-55B

■ Features

- Very low on-state resistance
- Q101 compliant
- 175°C rated
- Standard level compatible.



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Drain-source voltage	V _{DS}	55	V
Drain-gate voltage R _{GS} = 20 kΩ	V _{DGR}	55	V
Gate-source voltage	V _{GS}	±20	V
Drain current (DC) T _{mb} = 25°C, V _{GS} = 10 V	I _D	119	A
Drain current (DC) T _{mb} = 100°C, V _{GS} = 10 V	I _D	75	A
Drain current (pulse peak value) *1	I _{DM}	478	A
Total power dissipation T _{mb} = 25°C	P _{tot}	203	W
Storage & operating temperature	T _{stg} , T _j	-55 to 175	°C
reverse drain current (DC) T _{mb} = 25°C	I _{DR}	119	A
		75	A
pulsed reverse drain current *1	I _{DRM}	478	A
non-repetitive avalanche energy *2	E _{DS(AL)S}	351	J
Thermal resistance junction to mounting base	R _{th j-mb}	0.74	K/W
Thermal resistance junction to ambient	R _{th j-a}	50	K/W

* 1 T_{mb} = 25°C; pulsed; t_p ≤ 10 μs;

*2 unclamped inductive load; I_D = 75 A; V_{DS} ≤ 55 V; V_{GS} = 10 V; R_{GS} = 50Ω; starting T_{mb} = 25°C

KUK7607-55B■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	55			V
		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55^\circ\text{C}$	50			V
gate-source threshold voltage	$V_{GS(th)}$	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25^\circ\text{C}$	2	3	4	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175^\circ\text{C}$	1			V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55^\circ\text{C}$			4.4	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$		0.02	1	μA
		$V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175^\circ\text{C}$			500	μA
gate-source leakage current	I_{GSS}	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$		2	100	nA
drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 25^\circ\text{C}$.	5.8	7.1	$\text{m}\Omega$
		$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 175^\circ\text{C}$			14.2	$\text{m}\Omega$
total gate charge	$Q_{g(\text{tot})}$	$V_{GS} = 10 \text{ V}; V_{DD} = 44 \text{ V}; I_D = 25 \text{ A}$		53		nC
gate-to-source charge	Q_{gs}			12		nC
gate-to-drain (Miller) charge	Q_{gd}			17		nC
input capacitance	C_{iss}	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$		2820	3760	pF
output capacitance	C_{oss}			554	665	pF
reverse transfer capacitance	C_{rss}			200	274	pF
turn-on delay time	$t_{d(on)}$	$V_{DD} = 30 \text{ V}; R_L = 1.2\Omega; V_{GS} = 10 \text{ V}; R_G = 10\Omega$		24		ns
rise time	t_r			52		ns
turn-off delay time	$t_{d(off)}$			77		ns
fall time	t_f			41		ns
internal drain inductance	L_d	from drain lead 6 mm from package to centre of die		4.5		nH
				2.5		nH
internal source inductance	L_s	from source lead to source bond pad		7.5		nH
source-drain (diode forward) voltage	V_{SD}	$I_S = 40\text{A}; V_{GS} = 0 \text{ V}$		0.85	1.2	V
reverse recovery time	t_{rr}	$I_S = 25 \text{ A}; -dI/dt = -100 \text{ A}/\mu\text{s};$		62		ns
recovered charge	Q_r	$V_{GS} = -10 \text{ V}; V_{DS} = 30 \text{ V}$		60		nC